REFERENCES

1. Angie Fan, Richard Bonner, et al, An Innovative Passive Cooling Method for High Performance Light-emitting Diodes, 28th IEEE SEMI-THERM Symposium , IEEE , 2012, 978-1-4673-1111
2. Chen Jie, Chen Jie, et al, Heat Dissipation Simulation Research of LED Down light and Optimization of Light Source Layout, Proceedings of the 2nd International Conference on Computer Science and Electronics Engineering, ICCSEE, 2013
3. Diary R. Sulaiman , Microprocessors Thermal Challenges for Portable and Embedded
4. E. Hong, N. Narendran, A method for projecting useful life of LED lighting system, 2004, Proceeding of SPIE, 587, 93-99.
5. Heinle C, Drummer D. Potential of thermally conductive polymers for the cooling of mechatronic parts, Physics Procedia 5 , 2010, 735–744
6. Hou Fengze, Yang Daoguo, et al, Thermal analysis of LED lighting system with different fin heat sinks, Journal of Semiconductors, 2011, Vol. 32-1
7. Jingsong Li, Qingxin Yang, et al, Analysis of Thermal Field on Integrated LED Light Source Based on COMSOL Multi-physics Finite Element Simulation, Physics Procedia 22 ,2011, 150 – 156
8. Khan M.F. Shahil , Alexander A. Balandin , Thermal properties of graphene and multilayer graphene: Applications in thermal interface materials , Solid State Communications 152 ,2012, 1331–1340
9. LiuYi-bing, On Thermal Structure Optimization of a Power LED Lighting, Procedia Engineering 29, 2012, 2765 – 2769
10. M. Fathi, A. Chikouche and M. Abderrazak, Design and realization of LED Driver for solar street lighting applications, Energy Procedia 6 , 2011, 160–165
11. Marius Dillig, Jürgen Karl, Thermal management of high temperature solid oxide electrolyser cell/fuel cell systems , Energy Procedia 28 , 2012, 37 – 47
12. Minseok Ha, Samuel Graham , Development of a thermal resistance model for chip-on-board packaging of high power LED arrays, Microelectronics Reliability 52, 2012, 836–844
13. Minseok Ha, Samuel Graham, Development of a thermal resistance model for chip-on-board packaging of high power LED arrays, Microelectronics Reliability 52, 2012, 836–844

14. S. Shanmugan, D. Mutharasu, O. Zeng Yin, Performance of Light Emitting Diode on Surface Machined Heat Sink, International Journal of Power Electronics and Drive System (IJPEDS) ,Vol.2, No.4, 2012, 380~388
15. Shung-Wen Kang, Kun-Cheng Chien and Wei-Chung Lin, Thermal Analysis and Test of the Multiple-Layer Heat Dissipating Module for LED Streetlamps, 10th IHPS, Taipei, 2011.277-282
16. Systems Using Thermal Throttling Technique, Procedia Computer Science 3, 2011, 1023–1032
17. Ugo Lafont, Henk van Zeijl , Sybrand van der Zwaag , Increasing the reliability of solid state lighting systems via self-healing approaches: A review, Microelectronics Reliability 52 , 2012, 71–89
18. V.Vigh, L. Kalman, Investigation of the thermal management of a high power LED module, Bulletine of the Transilvania University of Brasov, 2013,seris-1,Vol-6(5)
19. Xiang-you Lu, Tse-Chao Hua, Yan-ping Wang, Thermal analysis of high power LED package with heat pipe heat sink, Microelectronics Journal 42, 2011, 1257–1262
20. Zeng Dehuai, Liu Yuan, et al, A Novel Manufacturing Approach of Phase-change Heat Sink for High-power LED, Energy Procedia 17, 2012, 1974 – 1979